

**REMARKS**

Claims 16-23, 25-32, 34-40, and 42-45 are pending in the application. Independent claims 16, 29, and 38 have been amended to recite that a plurality of support portions are formed at edge corners of a flat portion "therein." The amendments are fully supported by the application as originally filed (see, e.g., FIG. 3 of application).

As amended, independent claims 16, 29, and 38 each recite a heat dissipating structure for a semiconductor package including a flat portion and a plurality of support portions, where the support portions are "formed at edge corners of the flat portion therein," i.e., within or inside the flat portion (independent claim 16; *see also* independent claims 29 and 38; and FIG. 3).

Claims 29-32, 35-40, and 43-45 were rejected under 35 USC 103(a) as being unpatentable over U.S. Patent 6,580,167 to Glenn et al. ("Glenn") in view of "Applicant's admitted prior art" (hereinafter "AAPA"). Claims 34 and 42 were rejected under 35 USC 103(a) as being unpatentable over Glenn in view of AAPA, and further in view of U.S. Patent 6,246,115 to Tang et al. ("Tang"). Claims 16-23 and 26-28 were rejected under 35 USC 103(a) as being unpatentable over Glenn in view of AAPA and U.S. Patent 5,736,785 to Chiang et al. ("Chiang"). Claim 25 was rejected under 35 USC 103(a) as being unpatentable over Glenn in view of AAPA and Chiang, and further in view of Tang. These rejections are respectfully traversed.

The proposed combinations of Glenn in view of AAPA, Chiang, and/or Tang do not teach or suggest a heat dissipating structure having at least a flat portion and a plurality of support portions formed at edge corners of the flat portion therein for supporting the flat portion above a chip, such that the support portions do not interfere with the chip.

On pages 2-3 of the Office Action of 01/30/2007, a portion of FIG. 1 of Glenn was cited as allegedly corresponding to the claimed "flat portion," and legs 152 of Glenn were cited as allegedly corresponding to the claimed "support portions."

Glenn discloses a heat sink 130 for a semiconductor package, the heat sink 130 including a central body portion 136 and a projection ring 133 with four projections 134 (see column 5, lines 47-49). The projections 134 are used for supporting spring elements 150, which are cut from the projections 134 (see column 5, lines 61-63). The spring elements 150 "include legs 152 and feet 154" (see column 5, lines 63-64).

However, Glenn does not teach or suggest a heat dissipating structure having the claimed flat portion and support portions. In particular, independent claims 16, 29, and 28 each require that the support portions be formed at "edge corners of the flat portion therein," i.e., within or inside the flat portion.

In Glenn, the legs 152 extend in an area **beyond** the "flat portion" of FIG. 1 as identified in the Office Action. Therefore, the heat sink of Glenn does not correspond to the Applicant's claimed invention. Moreover, in Glenn, each leg 152 is cut from and extends downwardly from a projection 134, which requires a more complicated manufacturing process, and is not necessary or desirable in the Applicant's claimed invention.

Even if AAPA, Chiang, and/or Tang were somehow combined with Glenn, the proposed combination would not teach or suggest the Applicant's claimed invention as recited in independent claims 16, 29, and 38, for at least the reasons discussed above.

It is believed the application is in condition for immediate allowance, which action is earnestly solicited.

Respectfully submitted,

/Steven M. Jensen/

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